

## Amendments to the Specification

Please replace the paragraph beginning on page 5, line 1, with the following amended paragraph:

Figure 7B is a diagram of ~~is an exemplary~~ an exemplary sensor pattern that includes conductive bridges in accordance with an embodiment of the present invention for a capacitive sensing device.

Please replace the paragraph beginning on page 12, line 10, with the following amended paragraph:

Alternatively, capacitive sensor pattern 304 includes isolated diamond shapes 306, 308, 310, 312, 314 and 316 which can be disposed on the substantially transparent flexible substrate 301 as described herein. The diamond shapes 306, 308, 310, 312, 314 and 316 are electrically isolated and are therefore not yet useful as input to capacitive sensing circuitry. However, it is pointed out that the substantially transparent conductive material of the diamond shapes of capacitive sensor patterns 302 and 304 exist ~~with a single layer~~ within a single layer which is advantageous for fabricating a capacitive sensing device that is thin and flexible.

Please replace the paragraph beginning on page 22, line 6, with the following amended paragraph:

Within Figure 7A, it is noted that the substantially transparent flexible substrate 301 of the present embodiment may be implemented in a wide variety of ways. For example, the substantially transparent flexible substrate 301 can be implemented with, but is not limited to, PET. Additionally, the layer of substantially transparent conductive material of both capacitive sensor ~~patterns 302 and 304~~ patterns 302b and 304b can be implemented in diverse ways such as, but not limited to, ITO or any other substantially transparent conductive material. Furthermore, the layer of substantially opaque conductive material can be implemented in a wide variety of ways in accordance with the present embodiment. For example, the substantially opaque conductive material

can be implemented as, but not limited to, conductive ink (e.g., silver ink, carbon ink, mixture of silver and carbon inks, and the like).

Please replace the paragraph beginning on page 26, line 21, and ending on page 27, line 8, with the following amended paragraph:

Figure 11 is a side sectional view of an integrated keypad assembly in accordance with an embodiment of the present invention in which an integrated capacitive sensing device is integral to the keymat. Within keymat assembly 1100, which includes capacitive sensing device 1104, keys 1108 are formed as part of keymat portion 1102 which can be formed of a rubber material. It is noted that capacitive sensor device 1104 has been integrated within the rubber material of keymat assembly 1100. Specifically, keymat assembly 1100 includes a first keymat portion 1102 of rubber and a second keymat portion 1106 of rubber. As such, the capacitive sensor device 1104 is disposed between and within rubber portions 1102 and 1106. It is understood that keymat assembly 1100 operates in a manner similar to keypad ~~assembly 202 of~~ assembly 200 of Figure 2, described herein.

Please replace the paragraph beginning on page 27, line 16, and ending on page 28, line 9, with the following amended paragraph:

At operation 1202, a first pattern of conductive sensors is disposed above a substantially transparent substrate within a sensing region. The first pattern of conductive sensors has at least a portion thereof that includes a substantially transparent conductive material. It is noted that the disposing of the first pattern of conductive sensors at operation 1202 can also include disposing at least a first portion comprised of substantially opaque conductive material (e.g., conductive ink) that is electrically coupled to at least a second portion of the substantially transparent material (e.g., ITO) of the first pattern of conductive sensors. It is understood that the sensing region will be the area ~~proximate to~~ proximate to the capacitive sensing device for which the capacitive sensing device is designed to actively “capture” pointing and/or gesturing inputs of a finger of a user when it is in proximity to the capacitive sensing device. Furthermore, the disposing of the first pattern of conductive sensors at

operation 1202 can also include the first portion of the substantially opaque conductive material including openings formed therethrough such that light is able to pass through the openings of the substantially opaque conductive material. In one embodiment, the first portion of substantially opaque conductive material overlies at least a portion of the first pattern of conductive sensors.